

05-24-2002

6348/ETCH/SILICON



FORM PTO-1595 (Rev. 6-93) GPO No. 0551-0111 (Imp. 4/94)

RECO

U.S. Department of Commerce Patent and Trademark Office

102147996

5/14/02

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original document or copy thereof.

1. Name of conveying party(ies):
 Keiji Horioka 04-15-02 Douglas H. Burns 05-14-02
 Chun Yan 04-11-02 Evans Y. Lee 05-01-02
 Taeho Shin 04-08-02 Bryan Y. Pu 04-14-02
 Roger Alan Lindley 04-16-02
 Qi Li 05-06-02
 Panyin Hughes 04-16-02

2. Name and address of receiving party(ies):
 Name: Applied Materials, Inc.
 Internal Address: _____
 Street Address: 3050 Bowers Avenue
P.O. Box 450A
 City: Santa Clara State: CA Zip: 95054
 Additional name(s) & address(es) attached? ___ Yes X No

Additional names? ___ Yes X No

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other _____

Execution Date: SEE ABOVE

4. Application number(s) or registration number(s):

If this document is being filed together with a new application, the execution date of the application is: May 14, 2002 (Date of Filing)

A. Patent Application No.(s)

B. Patent No. (s)

Additional numbers attached? ___ Yes X No

10/146443

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Patent Counsel
 Internal Address: APPLIED MATERIALS, INC.
 Street Address: P.O. Box 450A
 City: Santa Clara State: CA Zip: 95052

6. Total number of applications and patents involved: 1

7. Total fee (37 C.F.R. 3.41)----- \$ 40.00

Enclosed
 Authorized to be charged to deposit account

50-1074

8. Deposit account number:

50-1074

05/23/2002 6TOM11 00000152 501074 10146443

01 FC:581 40.00 CH

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

ROBERT W. MULCAHY
 Name of Person Signing
 Registration No. 25,436

Signature

Date

5/14/02

Total number of pages including cover sheet, attachments and document: 19

Mail documents to be recorded with required cover sheet information to:
 Commissioner of Patents & Trademarks, Box Assignments
 Washington, D.C. 20231

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

- | | |
|-----------------------|---------------------|
| 1) Keiji Horioka | 6) Panyin Hughes |
| 2) Chun Yan | 7) Douglas H. Burns |
| 3) Taeho Shin | 8) Evans Y. Lee |
| 4) Roger Alan Lindley | 9) Bryan Y. Pu |
| 5) Qi Li | |

(hereinafter referred to as Assignors), have invented a certain invention entitled:

METHOD AND APPARATUS FOR CONTROLLING THE MAGNETIC FIELD INTENSITY IN A PLASMA ENHANCED SEMICONDUCTOR WAFER PROCESSING CHAMBER

for which application for Letters Patent in the United States was executed on even date herewith;
and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

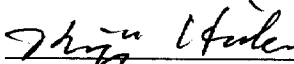
2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or

additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

- 1) Apr 15, 2002 
Keiji Horioka
- 2) _____, 2002 _____
Chun Yan
- 3) _____, 2002 _____
Taeho Shin
- 4) _____, 2002 _____
Roger Alan Lindley
- 5) _____, 2002 _____
Qi Li
- 6) _____, 2002 _____
Panyin Hughes
- 7) _____, 2002 _____
Douglas H. Burns
- 8) _____, 2002 _____
Evans Y. Lee
- 9) _____, 2002 _____
Bryan Y. Pu

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

- | | |
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| 1) Keiji Horioka | 6) Panyin Hughes |
| 2) Chun Yan | 7) Douglas H. Burns |
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additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

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IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) _____, 2002

Keiji Horioka

2) April 11, 2002



Chun Yan

3) _____, 2002

Taeho Shin

4) _____, 2002

Roger Alan Lindley

5) _____, 2002

Qi Li

6) _____, 2002

Panyin Hughes

7) _____, 2002

Douglas H. Burns

8) _____, 2002

Evans Y. Lee

9) _____, 2002

Bryan Y. Pu

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

- | | |
|-----------------------|---------------------|
| 1) Keiji Horioka | 6) Panyin Hughes |
| 2) Chun Yan | 7) Douglas H. Burns |
| 3) Taeho Shin | 8) Evans Y. Lee |
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additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

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IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

- 1) _____, 2002
Keiji Horioka
- 2) _____, 2002
Chun Yan
- 3) April 18, 2002

Taeho Shin
- 4) _____, 2002
Roger Alan Lindley
- 5) _____, 2002
Qi Li
- 6) _____, 2002
Panyin Hughes
- 7) _____, 2002
Douglas H. Burns
- 8) _____, 2002
Evans Y. Lee
- 9) _____, 2002
Bryan Y. Pu

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

- | | |
|-----------------------|---------------------|
| 1) Keiji Horioka | 6) Panyin Hughes |
| 2) Chun Yan | 7) Douglas H. Burns |
| 3) Taeho Shin | 8) Evans Y. Lee |
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1) _____, 2002

Keiji Horioka

2) _____, 2002

Chun Yan

3) _____, 2002

Taeho Shin

4) 4/16/02, 2002



Roger Alan Lindley

5) _____, 2002

Qi Li

6) _____, 2002

Panyin Hughes

7) _____, 2002

Douglas H. Burns

8) _____, 2002

Evans Y. Lee

9) _____, 2002

Bryan Y. Pu

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

- 1) Keiji Horioka
- 2) Chun Yan
- 3) Taeho Shin
- 4) Roger Alan Lindley
- 5) Qi Li
- 6) Panyin Hughes
- 7) Douglas H. Burns
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- 9) Bryan Y. Pu

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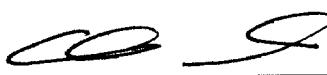
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- 1) _____, 2002

Keiji Horioka
- 2) _____, 2002

Chun Yan
- 3) _____, 2002

Taeho Shin
- 4) _____, 2002

Roger Alan Lindley
- 5) 5-6 _____, 2002


Qi Li
- 6) _____, 2002

Panyin Hughes
- 7) _____, 2002

Douglas H. Burns
- 8) _____, 2002

Evans Y. Lee
- 9) _____, 2002

Bryan Y. Pu

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

- | | |
|-----------------------|---------------------|
| 1) Keiji Horioka | 6) Panyin Hughes |
| 2) Chun Yan | 7) Douglas H. Burns |
| 3) Taeho Shin | 8) Evans Y. Lee |
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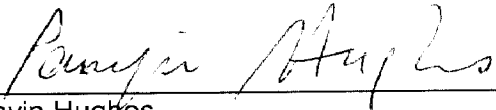
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|----|------------------------|--|--------------------|
| 1) | _____ , 2002 | _____ | Keiji Horioka |
| 2) | _____ , 2002 | _____ | Chun Yan |
| 3) | _____ , 2002 | _____ | Taeho Shin |
| 4) | _____ , 2002 | _____ | Roger Alan Lindley |
| 5) | _____ , 2002 | _____ | Qi Li |
| 6) | <u>APRIL 16</u> , 2002 |  | Panyin Hughes |
| 7) | _____ , 2002 | _____ | Douglas H. Burns |
| 8) | _____ , 2002 | _____ | Evans Y. Lee |
| 9) | _____ , 2002 | _____ | Bryan Y. Pu |

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

- | | |
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| 1) Keiji Horioka | 6) Panyin Hughes |
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IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

- 1) _____, 2002

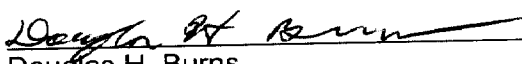
Keiji Horioka
- 2) _____, 2002

Chun Yan
- 3) _____, 2002

Taeho Shin
- 4) _____, 2002

Roger Alan Lindley
- 5) _____, 2002

Qi Li
- 6) _____, 2002

Panyin Hughes
- 7) 5-14, 2002


Douglas H. Burns
- 8) _____, 2002

Evans Y. Lee
- 9) _____, 2002

Bryan Y. Pu

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

- 1) Keiji Horioka
- 2) Chun Yan
- 3) Taeho Shin
- 4) Roger Alan Lindley
- 5) Qi Li
- 6) Panyin Hughes
- 7) Douglas H. Burns
- 8) Evans Y. Lee
- 9) Bryan Y. Pu

(hereinafter referred to as Assignors), have invented a certain invention entitled:

METHOD AND APPARATUS FOR CONTROLLING THE MAGNETIC FIELD INTENSITY IN A PLASMA ENHANCED SEMICONDUCTOR WAFER PROCESSING CHAMBER

for which application for Letters Patent in the United States was executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or

additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

- | | | | | | |
|----|------------|--------|--------|--------------------|--------------|
| 1) | _____ | , 2002 | _____ | Keiji Horioka | |
| 2) | _____ | , 2002 | _____ | Chun Yan | |
| 3) | _____ | , 2002 | _____ | Taeho Shin | |
| 4) | _____ | , 2002 | _____ | Roger Alan Lindley | |
| 5) | _____ | , 2002 | _____ | Qi Li | |
| 6) | _____ | , 2002 | _____ | Panyin Hughes | |
| 7) | _____ | , 2002 | _____ | Douglas H. Burns | |
| 8) | <i>5/1</i> | _____ | , 2002 | _____ | Evans Y. Lee |
| 9) | _____ | , 2002 | _____ | Bryan Y. Pu | |

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

- 1) Keiji Horioka
- 2) Chun Yan
- 3) Taeho Shin
- 4) Roger Alan Lindley
- 5) Qi Li
- 6) Panyin Hughes
- 7) Douglas H. Burns
- 8) Evans Y. Lee
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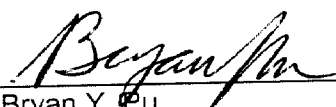
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additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

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| 6) | _____ , 2002 | _____ | Panyin Hughes |
| 7) | _____ , 2002 | _____ | Douglas H. Burns |
| 8) | _____ , 2002 | _____ | Evans Y. Lee |
| 9) | <u>4-14-02</u> , 2002 |  | Bryan Y. Fu |